

In the claims:

1. (currently amended) A method of backgrinding a wafer, said wafer characterized by a front side and a backside, said method comprising the steps of:

providing tape and a chuck, said tape suitable for protecting a wafer during backgrinding and said chuck suitable for use during backgrinding of the wafer;

placing the tape onto the chuck;

placing the wafer onto the tape with the front side of the wafer facing the tape;

thereafter backgrinding the backside of the wafer;

before removing the wafer from the tape, spraying the backside of the wafer with water under a pressure of about 40 PSI to about 60 PSI while scrubbing the backside of the wafer;

removing the wafer from the tape while leaving the tape on the chuck;

thereafter cleaning the front side of the wafer, wherein the step of cleaning the front side of the wafer comprises spraying the front side of the wafer with water under a pressure of about 500 PSI to about 1500 PSI while scrubbing the front side of the wafer; and

drying the wafer.

2. (canceled)

3. (currently amended) A method of preparing a wafer, said method comprising the steps of:

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- a) providing a wafer having a front side and a backside;
- b) processing the wafer such that the wafer has a flatness and a thickness suitable for building-up a device on the front side of the wafer;
- c) building-up a device onto the front side of the wafer;
- d) providing a chuck and a tape, wherein the chuck is suitable for supporting the tape during a backgrinding process, and wherein the tape is suitable for supporting the wafer;
- e) after building up the device, placing the tape onto the chuck;
- f) placing the front side of the wafer onto the tape;
- g) securing the front side of the wafer to the tape;
- h) grinding the backside of the wafer;
- i) before removing the wafer from the tape, spraying the backside of the wafer with water under a pressure of about 500 PSI to about 1500 PSI while scrubbing the backside of the wafer;
- j) ~~i)~~ removing the wafer from the tape;
- k) ~~j)~~ thereafter cleaning the front side of the wafer, wherein the step of cleaning the front side of the wafer comprises spraying the front side of the wafer with water under a pressure of about 500 PSI to about 1500 PSI while scrubbing the front side of the wafer; and

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1) ~~*~~ drying the wafer.

4. (canceled)

5. (canceled)

6. (canceled)

7. (canceled)

8. (canceled)

9. (canceled)

10. (canceled)

11. (currently amended) A method of backgrinding a wafer, said wafer characterized by a front side and a backside, said method comprising the steps of:

providing a mesh and a chuck, said mesh suitable for protecting a wafer during backgrinding and said chuck suitable for use during backgrinding of the wafer;

placing the mesh onto the chuck;

placing the wafer onto the mesh with the front side of the wafer facing the mesh;

thereafter backgrinding the backside of the wafer;

before removing the wafer from the tape, spraying the backside of the wafer with water under a pressure of about 500 PSI to about 1500 PSI while scrubbing the backside of the wafer;

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removing the wafer from the mesh while leaving the mesh on the chuck;

thereafter cleaning the front side of the wafer, wherein the step of cleaning the front side of the wafer comprises spraying the front side of the wafer with water under a pressure of about 500 PSI to about 1500 PSI while scrubbing the front side of the wafer; and

drying the wafer.

12. (canceled)